



## P-Ch 100V Fast Switching MOSFETs

## Description

The HSH0139 uses advanced trench MOSFET technology to provide excellent  $R_{DS(ON)}$  and gate charge for use in a wide variety of other applications.

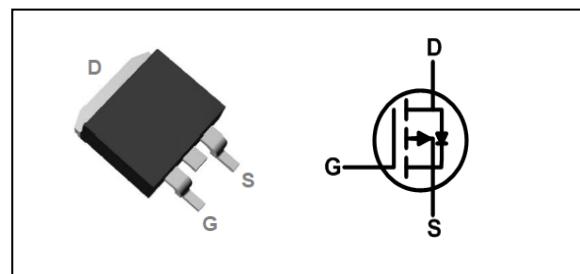
The HSH0139 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

## Product Summary

$V_{DS}$	-100	V
$R_{DS(ON),max}$	50	$m\Omega$
$I_D$	-35	A

## TO-263 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-35	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-23	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-100	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	345	mJ
$I_{AS}$	Avalanche Current	28	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation <sup>4</sup>	104	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	1.2	°C/W

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**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_D=-250\mu\text{A}$	-100	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$\text{V}_{\text{GS}}=-10\text{V}$ , $\text{I}_D=-10\text{A}$	---	42	50	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-4.5\text{V}$ , $\text{I}_D=-8\text{A}$	---	46	55	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$ , $\text{I}_D=-250\mu\text{A}$	-1.2	-1.8	-2.5	V
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=-100\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $\text{T}_J=25^{\circ}\text{C}$	---	---	-50	$\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$\text{g}_{\text{fs}}$	Forward Transconductance	$\text{V}_{\text{DS}}=-10\text{V}$ , $\text{I}_D=-10\text{A}$	---	32	---	S
$\text{Q}_{\text{g}}$	Total Gate Charge	$\text{V}_{\text{DS}}=-80\text{V}$ , $\text{V}_{\text{GS}}=-10\text{V}$ , $\text{I}_D=-14\text{A}$	---	92	---	$\text{nC}$
$\text{Q}_{\text{gs}}$	Gate-Source Charge		---	17.5	---	
$\text{Q}_{\text{gd}}$	Gate-Drain Charge		---	14	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=-50\text{V}$ , $\text{V}_{\text{GS}}=-10\text{V}$ , $\text{R}_G=3.3\Omega$ , $\text{I}_D=14\text{A}$	---	20.5	---	$\text{ns}$
$\text{T}_r$	Rise Time		---	32.2	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	123	---	
$\text{T}_f$	Fall Time		---	63.7	---	
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{DS}}=-25\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	6516	---	$\text{pF}$
$\text{C}_{\text{oss}}$	Output Capacitance		---	223	---	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		---	125	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{I}_s$	Continuous Source Current <sup>1,5</sup>	$\text{V}_G=\text{V}_D=0\text{V}$ , Force Current	---	---	-35	A
$\text{V}_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_s=-1\text{A}$ , $\text{T}_J=25^{\circ}\text{C}$	---	---	1.2	V
$\text{t}_{\text{rr}}$	Reverse Recovery Time	$\text{I}_F=-14\text{A}$ , $\text{di}/\text{dt}=-100\text{A}/\mu\text{s}$ , $\text{T}_J=25^{\circ}\text{C}$	---	31.2	---	nS
$\text{Q}_{\text{rr}}$	Reverse Recovery Charge		---	31.97	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $\text{V}_{\text{DD}}=-25\text{V}$ , $\text{V}_{\text{GS}}=-10\text{V}$ , $\text{L}=0.88\text{mH}$ , $\text{I}_{\text{AS}}=-28\text{A}$
- 4.The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature
- 5.The data is theoretically the same as  $\text{I}_D$  and  $\text{I}_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



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Typical Characteristics

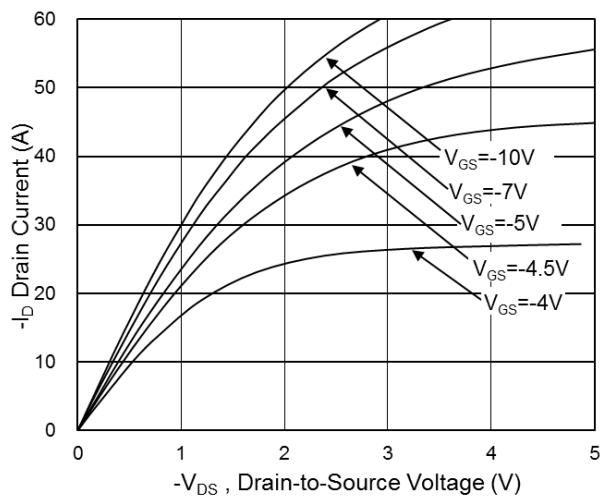


Fig.1 Typical Output Characteristics

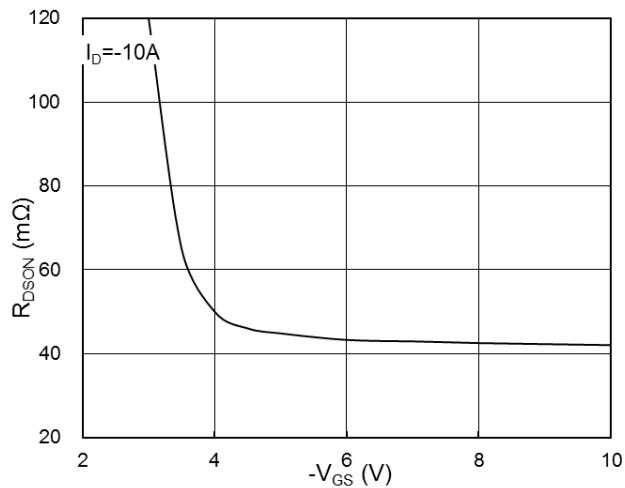


Fig.2 On-Resistance vs. G-S Voltage

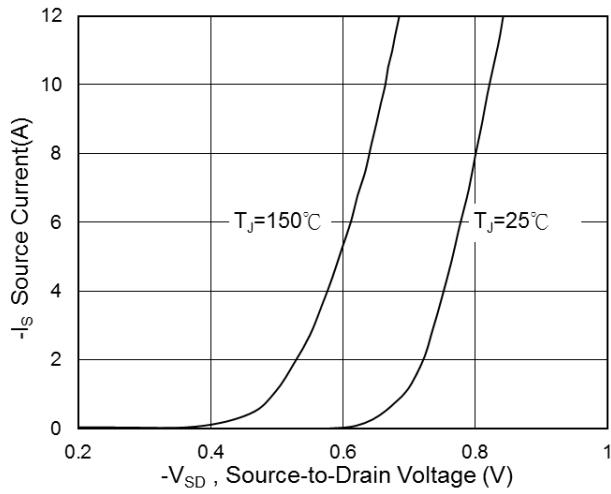


Fig.3 Typical S-D Diode Forward Voltage

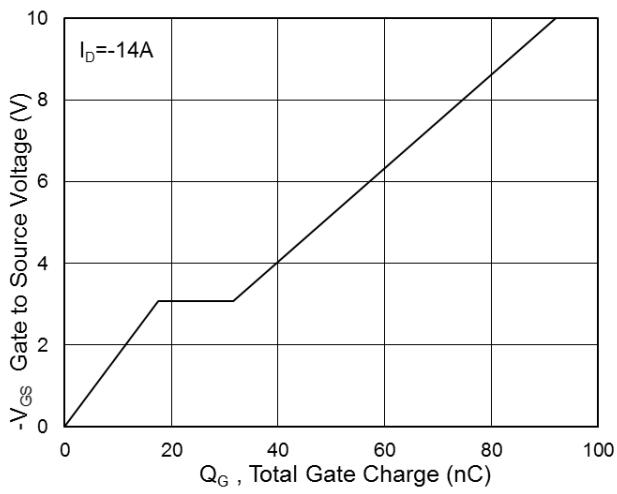


Fig.4 Gate-Charge Characteristics

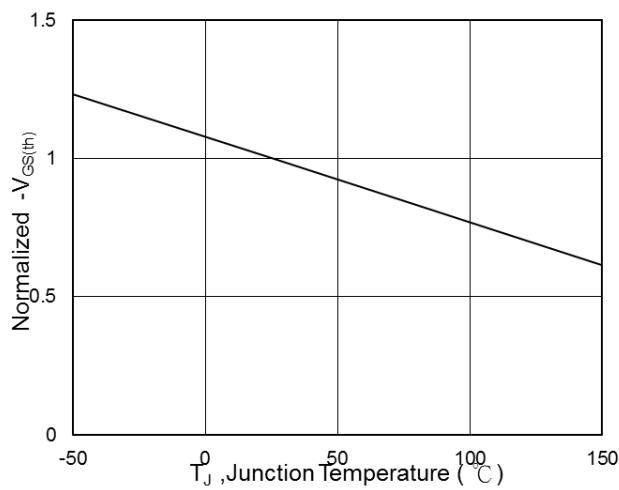


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

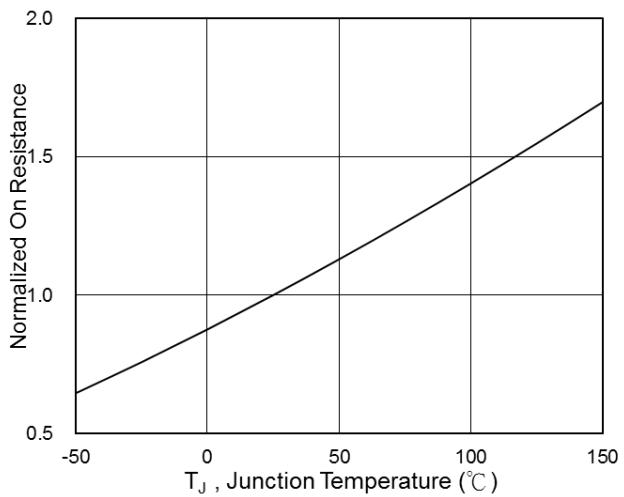


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$



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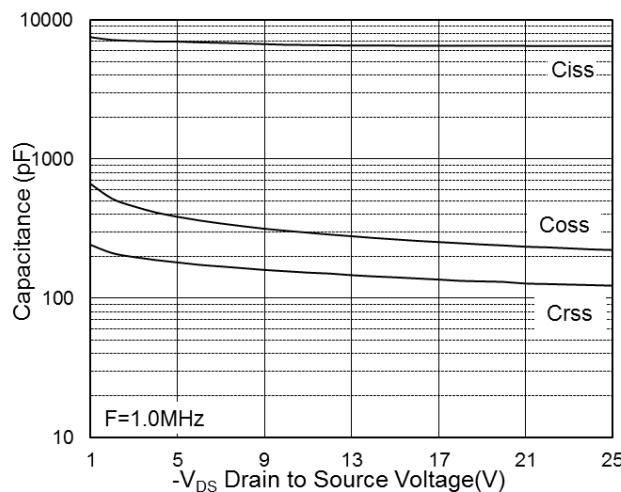


Fig.7 Capacitance

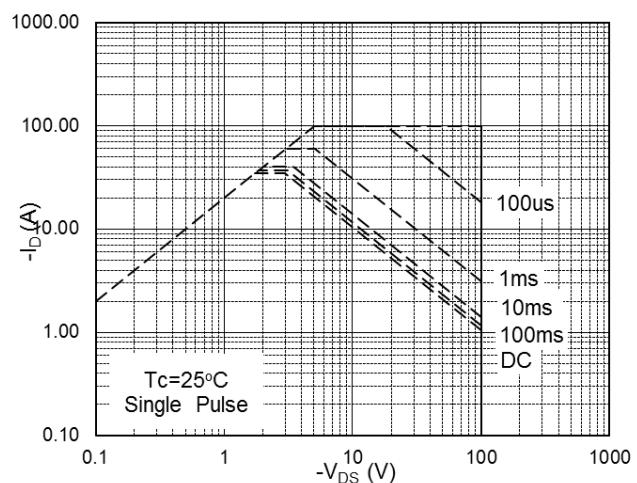


Fig.8 Safe Operating Area

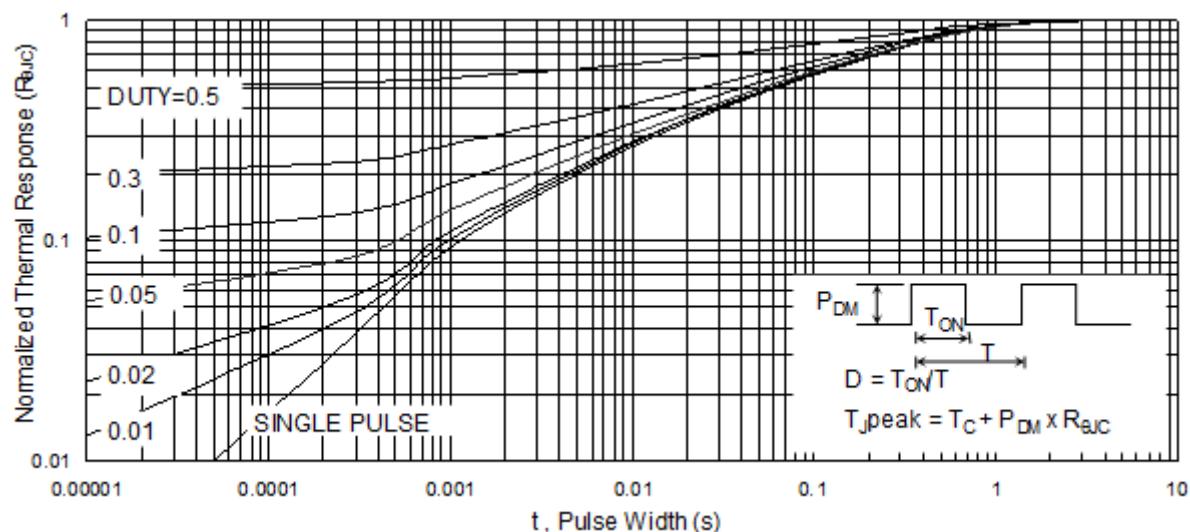


Fig.9 Normalized Maximum Transient Thermal Impedance

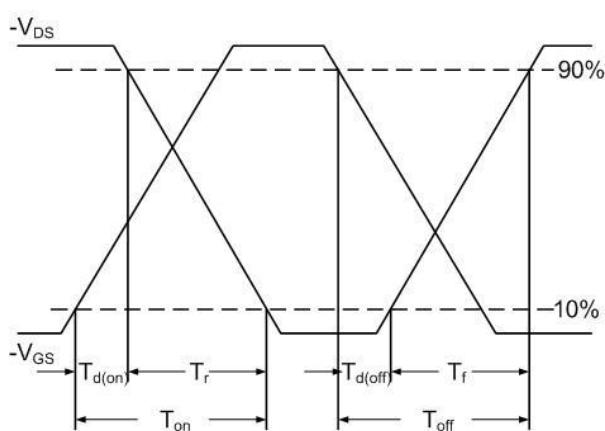


Fig.10 Switching Time Waveform

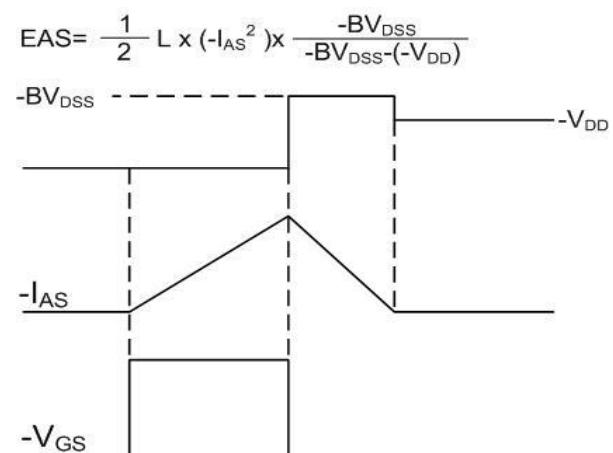
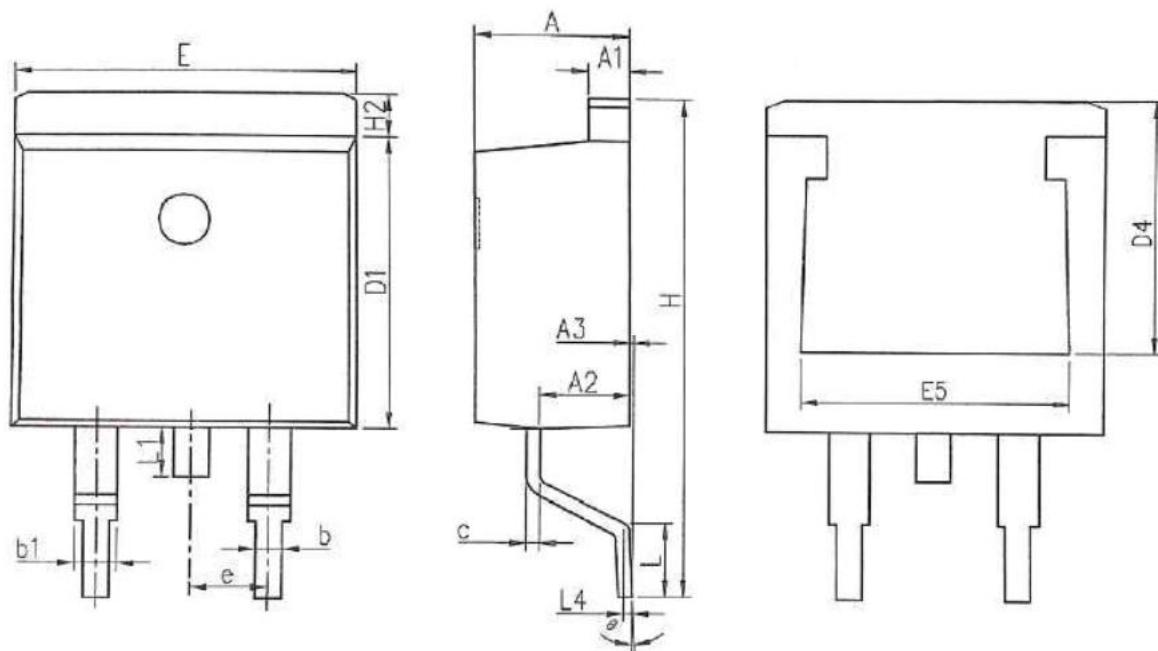


Fig.11 Unclamped Inductive Waveform



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SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.370	4.770	0.172	0.188
A1	1.220	1.420	0.048	0.056
A2	2.200	2.890	0.087	0.114
A3	0.000	0.250	0.000	0.010
b	0.700	0.960	0.028	0.038
b1	1.170	1.470	0.046	0.058
c	0.300	0.530	0.012	0.021
D1	8.500	9.300	0.335	0.366
D4	6.600	-	0.260	-
E	9.860	10.36	0.388	0.408
E5	7.060	-	0.278	-
e	2.540 BSC		0.100 BSC	
H	14.70	15.70	0.579	0.618
H2	1.070	1.470	0.042	0.058
L	2.000	2.600	0.079	0.102
L1	1.400	1.750	0.055	0.069
L4	0.250 BSC		0.010 BSC	
Θ	0°	9°	0°	9°